

Features

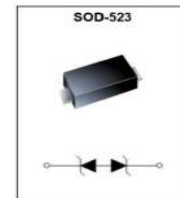
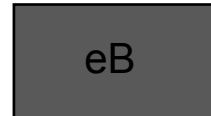
Bi-directional ESD protection of one line
Reverse stand-off voltage: 3.3V
Low reverse clamping voltage
Low leakage current
Fast response time
IEC 61000-4-2 (ESD) immunity test :
Air discharge: ±30kV
Contact discharge: ±30kV

Mechanical Data

SOD523 package
Molding compound flammability rating: UL 94V-0
Packaging: Tape and Reel
RoHS/WEEE Compliant

Applications

Computers and peripherals
High speed data lines
Audio and video equipment
Cellular handsets and accessories
Subscriber identity module(SIM) card protection
Portable electronics
FireWire
Other electronics equipments communi- cation systems



SOD-523
Schematic & PIN Configuration

Absolute Maximum Rating

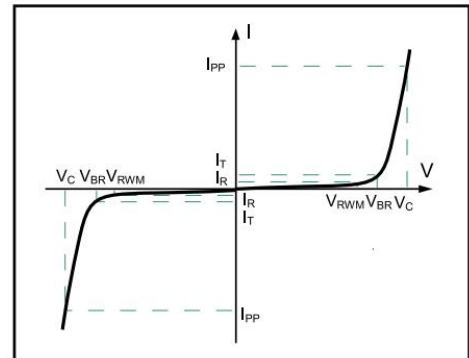
Parameter	Symbol	Value	Unit
Peak Pulse Power (8/20μs)	Ppk	80	W
Peak Pulse Current (8/20μs)	IPP	8	A
ESD per IEC 61000-4-2 (Air)	VESD	±30	kV
ESD per IEC 61000-4-2 (Contact)		±30	
Operating Temperature Range	TJ	-55to +125	°C
Storage Temperature Range	Tstg	-55 to +150	°C

Electrical Characteristics

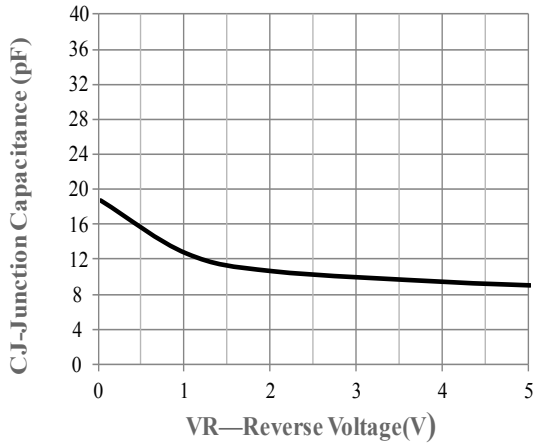
Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Reverse Working Voltage	V_{RWM}				3.3	V
Breakdown Voltage	V_{BR}	$I_T = 1mA$	3.5		6	V
Reverse Leakage Current	I_R	$V_{RWM} = \pm 3.3V$			0.1	μA
Clamping Voltage	V_C	$I_{PP} = 8A$ (8 x 20 μs pulse)			10	V
Junction Capacitance	C_j	$V_R = 0V, f = 1MHz$			20	pF

Electronics Parameter

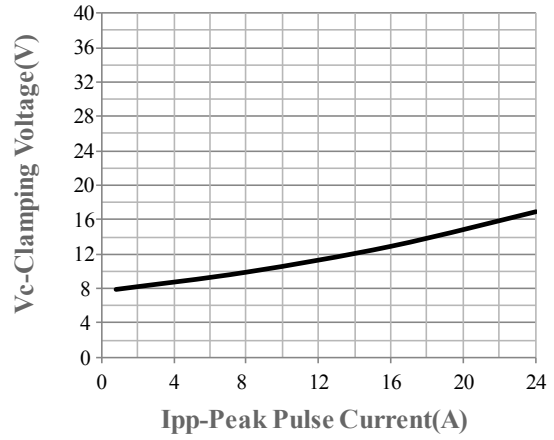
Symbol	Parameter
I_T	Test Current
I_{PP}	Maximum Reverse Peak Pulse Current
V_C	Clamping Voltage @ I_C
V_{BR}	Breakdown Voltage @ I_T
I_R	Reverse Leakage Current @ V_{RWM}
V_{RWM}	Reverse Standoff Voltage



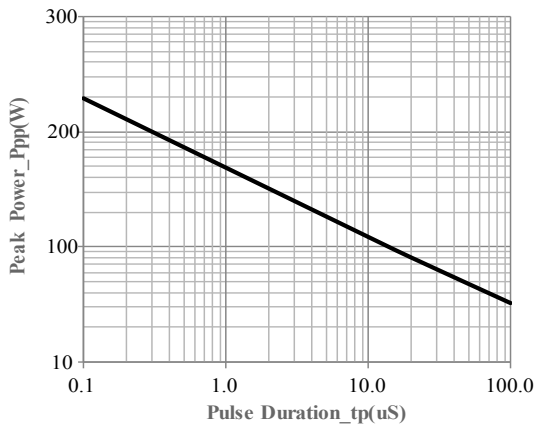
RATING AND CHARACTERISTIC CURVES



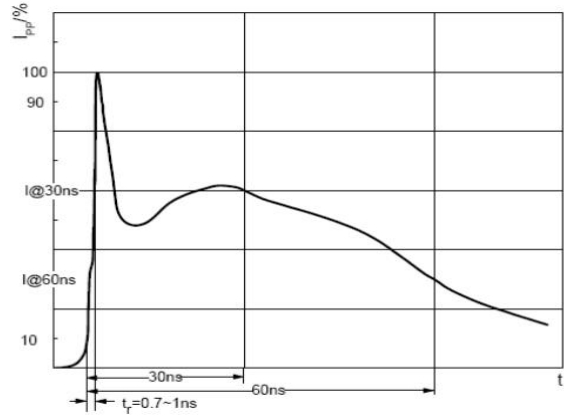
Junction Capacitance vs. Reverse Voltage



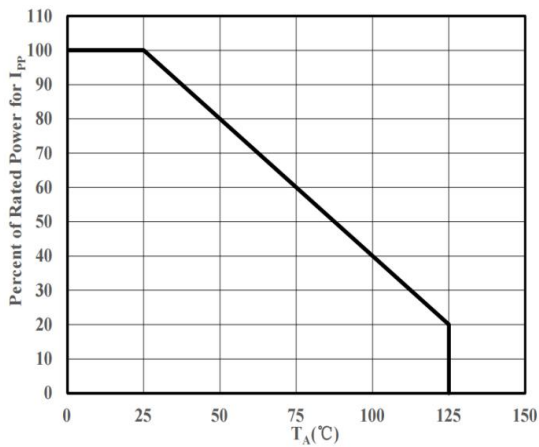
Clamping Voltage vs. Peak Pulse Current



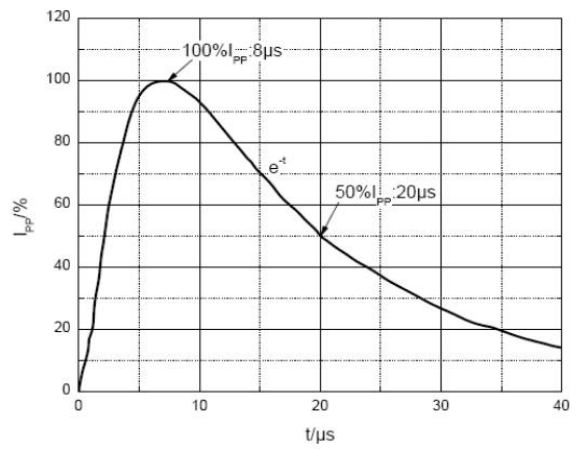
Peak Pulse Power vs. Pulse Time



ESD pulse waveform according to IEC61000-4-2



Power Derating Curve



8/20uS pulse waveform according to IEC 61000-4-5

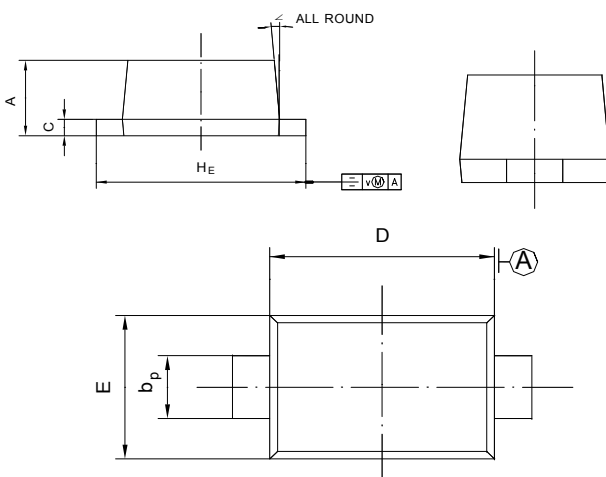
Soldering parameters

Reflow Condition		Pb-Free assembly (see as below)
Pre Heat	-Temperature Min ($T_{s(min)}$)	+150°C
	-Temperature Max($T_{s(max)}$)	+200°C
	-Time (Min to Max) (ts)	60-180 secs.
Average ramp up rate (Liquid us Temp (T_L) to peak)		3°C/sec. Max
$T_{s(max)}$ to T_L - Ramp-up Rate		3°C/sec. Max
Reflow	-Temperature(T_L)(Liquid us)	+217°C
	-Temperature(t_L)	60-150 secs.
Peak Temp (T_P)		+260(+0/-5)°C
Time within 5°C of actual Peak Temp (t_p)		30 secs. Max
Ramp-down Rate		6°C/sec. Max
Time 25°C to Peak Temp (T_P)		8 min. Max
Do not exceed		+260°C

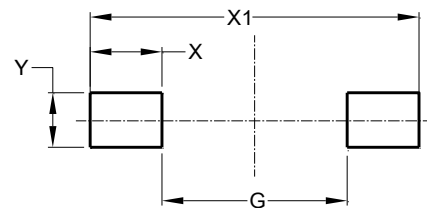


Package Dimensions & Suggested Pad Layout

SOD523



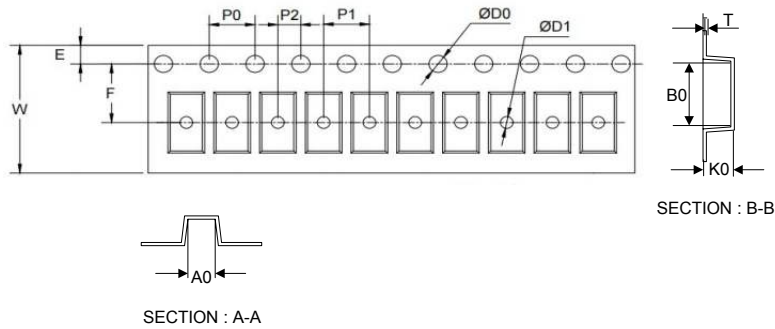
UNIT	A	b _p	C	D	E	H _E	V	∠
mm	0.70 0.50	0.40 0.20	0.14 0.05	1.30 1.10	0.90 0.75	1.70 1.50	0.1	5°



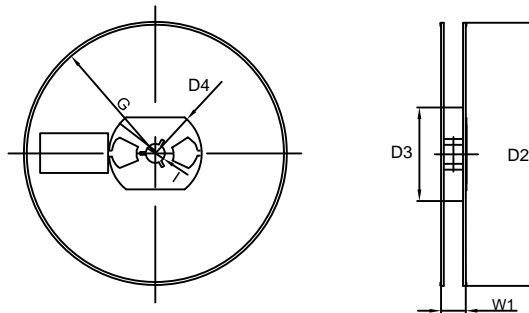
Dimensions	Value (in mm)
G	0.85
X	0.70
X1	2.25
Y	0.80

Tape & reel specification

Tape



7" Reel



Symbol	Dimension (mm)
P0	4.00±0.20
P1	2.00±0.20
P2	2.00±0.20
D0	1.55±0.20
D1	0.50±0.20
E	1.55±0.25
F	3.60±0.20
W	8.00±0.20
A0	1.30±0.20
B0	2.35±0.20
K0	0.95±0.20
T	0.20±0.20
D2	177.0±5.0
D3	55Min.
D4	R24.6±2.0
G	R82.0±2.0
I	13.0±2.0
W1	10.20±3.0
Quantity: 3000PCS	